

**APPLICATION DATA SHEET**  
**UNDER 37 CFR §1.76**

(1) Inventor Information

Inventor One Given Name::	Jong Soo
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Inventor Three Given Name::	Sung Jae
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(2) Assignee Information

Name Line One::	MK ELECTRON CO., LTD.
Address Line One::	316-2 Keumuh-ri, Pogok-myun
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City::	Yongin-city
State or Province::	Republic of Korea

(3) Correspondence Information

Customer No.: 3624  
Name Line One: Ruy M. Garcia-Zamor  
Name Line Two: Volpe and Koenig, P.C.  
Telephone No.: 215-568-6400

(4) Application Information

Title Line One: GOLD ALLOY BONDING WIRE FOR  
Title Line Two: SEMICONDUCTOR DEVICE  
Total Drawing Sheets: 3  
Drawing Type: Formal  
Application Type: Utility  
Docket No.: YPL-PT015

(5) Representative Information

Representative Customer No.: 3624

(6) Foreign Priority Information

Foreign Application One: 10-2003-0023344  
Filing Date: April 14, 2003  
Country: Korea  
Priority Claimed: YES